

Hyve Solutions Ambient Series-E

Revision 1.2 09/22/2017

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2. Revision History

Rev 1.1-041717	OCP Submission
Rev 1.2-092217	Added revision history, updated board jumper layout to add J20-
	J23, updated Prescribed Materials section.





3. Scope

This document defines the technical specifications for the Hyve Solutions Ambient Series-E server, including motherboard, chassis and power supply. The motherboard conforms to the existing Decathlete specification. Information about Intel's Decathlete server board can be found here (<u>Decathlete Server Board Standard v2</u>). The Decathlete standard provides board-specific information detailing the features and functionality of a general-purpose 2-socket server board for adoption by the Open Compute Project community.

4. License

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5. Overview

When data center design and hardware design move in concert, they can improve efficiency and reduce power consumption. To this end, the Open Compute Project is a set of technologies that reduces energy consumption and cost, increases reliability and choice in the marketplace, and simplifies operations and maintenance. One key objective is openness – the project is starting with the opening of the specifications and mechanical designs for the major components of a data center, and the efficiency results achieved at facilities using Open Compute technologies.





The Hyve Solutions Ambient Series-E incorporates a dual-socket motherboard, a chassis and power supply. The Ambient Series-E was designed to fit into standard 19" rail racks, allowing customers to take advantage of the price and power efficiency benefits of OCP without major data center retrofitting. It is 1U in height and is designed to work in both traditional datacenters as well as those using elevated ambient inlet temperatures.

6. Conformance to Decathlete v2.1 Specification

The motherboard used in the Ambient Series-E servers conform to the existing Decathlete specification. Information about Intel's Decathlete server board can be found here (<u>Decathlete Server Board Standard v2</u>). The Decathlete standard provides board-specific information detailing the features and functionality of a general-purpose 2-socket server board for adoption by the Open Compute Project community.

7. Motherboard Introduction

The Hyve Solutions Ambient Series-E is based on the Intel C612 chipset. The motherboard is designed to support dual Intel Xeon E5-2600 v3 and v4 series processors and up to 2048GB LRDIMM 3DS/1024GB LRDIMM/ 512GB RDIMM DDR4 memory. Leveraging advanced technology from Intel, the motherboard is capable of offering scalable 32- and 64- bit computing, high-bandwidth memory design, and lightning-fast PCI-E bus implementation.

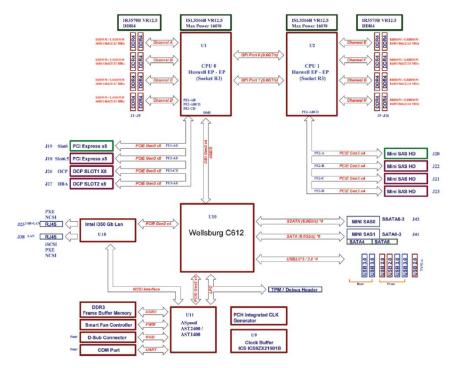


Figure 1: Motherboard block diagram





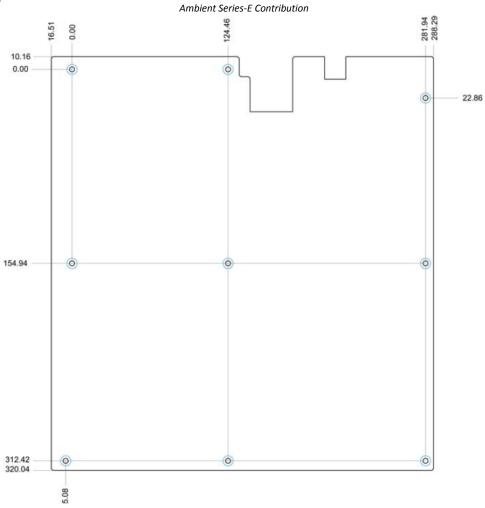


Figure 2: PCB Size - 12" W x 13" L





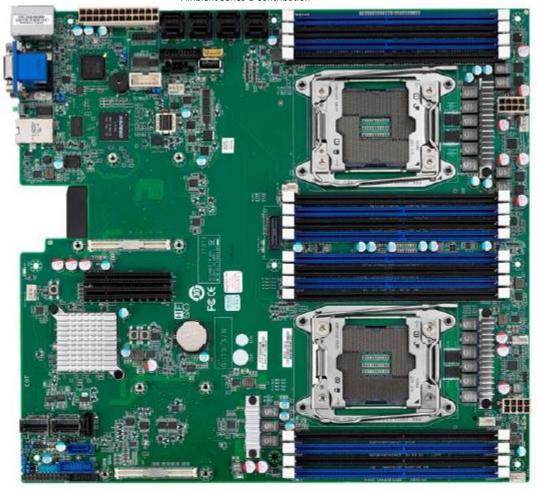


Figure 3: Board image

8. Motherboard Technical Specification

Form Factor EATX							
	■ 12" x 13" (305x330mm)						
Processor Intel Xeon E5-2600v3 & v4, specific DDR4 Models							
	■ Socket-R3 (LGA2011)						
	Count: 2						
	■ TDP=Max up to 160W						
■ Up to 9/6/8.0/6.4 GT/s with Intel QuickPath Interconnect (QPI) supported.							
Chipset	■ Intel C612 PCH						
Memory	■ DIMM Type: RDIMM DDR4, LRDIMM 3DS DDR4, LRDIMM DDR4						
	■ DIMM Socket Count: 16 @ 2 per Channel						
	DIMM Operating Speed:						
	RDIMM LRDIMM 3DS DDR4 LRDIMM DDR4						
	Speed 2133/1866/1600 2133/1600 2133/1600						
PCIe Port	PO						
Assignments	■ Port0 DMI2 = PCH						
	Port 1A+1B=Primary PCIe v3.0 x8 slot						
	Port 2A+2B=Primary PCIe v3.0 x8 slot						





Port 2C+2D= Ethernet OCP Mezzanine v0.5 , x8 PCle v3.0 Port 3A+3B=HBA Mezzanine, x8 PCle v3.0 P1 Port 2A+2B+2C+2D= (4) Internal Mini SAS HD, Each w/ x4 PCle v3.0 LAN Two GbE ports supported, LAN1 shared with IPMI Intel I350-AM2 Storage Intel C612 Controller (2) discrete SATA 7pin for SATA4 and SATA5 (2) MiniSAS SFF-8087 for SATA0~SATA3, sSATA0~sSATA3 6.0Gb/s speed	
P1 Port 2A+2B+2C+2D= (4) Internal Mini SAS HD, Each w/ x4 PCle v3.0 LAN Two GbE ports supported, LAN1 shared with IPMI Intel I350-AM2 Storage Intel C612 Controller (2) discrete SATA 7pin for SATA4 and SATA5 (2) MiniSAS SFF-8087 for SATA0~SATA3, sSATA0~sSATA3 6.0Gb/s speed	
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 (2) MiniSAS SFF-8087 for SATA0~SATA3, sSATA0~sSATA3 6.0Gb/s speed 	
■ 6.0Gb/s speed	
· ·	
■ SATA SGPIO supported	
■ RAID 0/1/10/5 (Intel RST)	
(4) Internal MiniSASHD SFF-8643 connectors (Optional)	
(4) internal willisasing str-8043 conflectors (Optional)	
BMC Type: ASPEED AST2400, Dedicated BMC Port, IPMI 2.0 or DCMI Compatible	
Console Port Speed: 115200	
Console Port Mapping: ttyS1	
Video ■ Chipset ASPEED AST2400	
■ Type: VGA, D-Sub 15 pin on board	
■ UP to 1920x1200	
Periphery I/O USB	
(3) USB2.0 ports (2 via cable, 1 vertical type-A connector	
(4) USB3.0 ports (2 at rear, 2 via cable)	
СОМ	
(2) ports (COM1 at rear, COM2 via cable)	
VGA	
(1) D-Sub 15 pin VGA port	
RJ-45	
(2) GbE ports, LAN1 shared with IPMI	
Power	
SSI 24-pin + 8-pin + 8-pin power connector	
• (1) PSMI 1x5-pin header	
SATA	
(2) SATA 7-pin connectors	
• (2) MiniSAS (4-in-1) connectors	
System Monitor & ASPEED AST2400	-
LED indicator • Monitor voltage for CPU, Memory, Chipset and Power Supply	
• (7) FAN 4-pin header	
 Temperature Monitor temperature for CPU and System environment 	
 Temperature warning indicator (Optional on Front Panel Board) 	
FAN and PSU fail LED indicator (Optional on Front Panel Board)	
 Watchdog timer supported 	
System • IPMI 2.0 compliant baseboard management controller	_
Management Support storage over IP and remote platform flash	
 USB2.0 virtual hub 	
 24-bit high quality video compression 	
■ 10/100 Mb/s MAC interface	
BIOS • AMI / 16MB	
 User-configurable HW monitoring 	
= CMDIOC 2.7 / Dap / Make an LAN / DVE hard suggested / ACDI 2.2 / ACDI 3.	eping
 SMBIOS 2.7 / PnP / Wake on LAN / PXE boot supported / ACPI 3.0 / ACPI sle 	





TPM	Type: Multi-Sourced, Modular
Operating System	 Windows 7 SP1 32-bits / Windows 7 SP1 64-bits / Windows 8 32-bits /Windows 8 64-bits / Windows 8.1 32-bits / Windows 8.1 64-bits / Windows Server 2008-R2 SP1 64-bits / Windows Server 2012-R2 SP1 64-bits RHEL 5 32-bits / RHEL 5 64-bits / RHEL 6 32-bits / RHEL 6 64-bits / RHEL 7 64-bits SLES 10 32-bits / SLES 10 64-bits / SLES 11 32-bits / SLES 11 64-bits
System Operating Environment	 Operating Temp 0-40° C Non-operating -40° C ~ 70° C (-40° F ~ 158° F) In/Non-operating Humidity 10% to 90% (non-condensing)
RoHS	RoHS6/6 Compliant

9. Motherboard Features

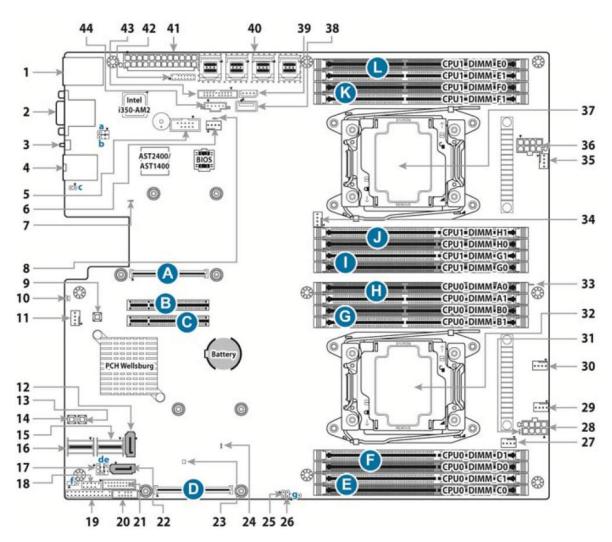


Figure 4: Board parts, jumpers & connectors





Connecto	or/Jumper			
1 LAN2 + USB 3.0 x 2	23 PCH PWROK LED (LED2)			
2 VGA / COM1	24 CAT Error LED (LED3)			
3 ID LED Button (SW3)	25 ID LED Button Header (J56)			
4 LAN1	26 Chassis Intrusion Header (J57)			
5 COM2 Header (J68)	27 CPU0 FAN (J28)			
6 SYS_FAN_4 (J31)	28 SSI 8-pin CPU0 Power Connector (PW1)			
7 BMC LED (LED1)	29 SYS_FAN_3 (J35)			
8 PSU Alert LED (LED10)	30 SYS_FAN_2 (J34)			
9 Clear CMOS Button (SW4)	31 CPU0 PWOK LED (LED8)			
10 Rear ID LED (LED7)	32 CPU0 Socket (U1)			
11 SYS_FAN_5 (J32)	33 CPU1 PWOK LED (LED9)			
12 7-pin Vertical SATA3.0 Connector (SATA5, J46)	34 CPU1 FAN (J30)			
13 Reset Button (SW2)	35 SYS_FAN_1 (J33)			
14 Power Button (SW1)	36 SSI 8-pin CPU1 Power Connector (PW3)			
15 SATA0~SATA3 (J41)	37 CPU1 Socket (U2)			
16 sSATA0~sSATA3 (J42)	38 Vertical Type-A USB2.0 Connector (J40)			
17 HOST SMBUS Header (J61)	39 IPMB Pin Header (J51)			
18 USB2.0 Header (J37)	40 Mini-SAS HD Connector (J20/J21/J22/J23)			
19 Front Panel Header (J50)	41 ATX 24-pin Main Power Connector (PW2)			
20 PCH SATA SGPIO Header for BB HD Board (J43)	42 TYAN Module Header (J48)			
21 USB3.0 Header (J36)	43 FAN Header for BB FAN Board (J29)			
22 7-pin Vertical SATA3.0 Connector (SATA4, J45)	44 PSMI Pin Header (J49)			
Jumpers	Slots			
a COM2 or COM5 Selected Jumper (J64)	A OCP Slot for OCP Mezz Card (J26)			
b COM2 or COM5 Selected Jumper (J63)	B PCI-E 3.0x8 Slot (x8 link, open-end type, #PCIe-6.5)			
c BMC Reset Header (J55)	C PCI-E 3.0x8 Slot (x8 link, open-end type, #PCIe-6)			
d BIOS Recovery Mode Jumper (J58)	D Proprietary Slot for SAS Mezz Card (J27)			





e NMI Jumper (J67)	E CPU0_DIMM_C0/C1
f ME Recovery Mode Jumper (J62)	F CPU0_DIMM_D0/D1
g ME Security Override Jumper (J60)	G CPU0_DIMM_B0/B1
	H CPU0_DIMM_A0/A1
	I CPU1_DIMM_G0/G1
	J CPU1_DIMM_H0/H1
	K CPU1_DIMM_F0/F1
	L CPU1_DIMM_E0/E1

Jumper Legend:

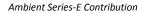
OPEN - Jumper OFF	Without jumper cover
CLOSED - Jumper ON	With jumper cover

Pinout of J20-J23:

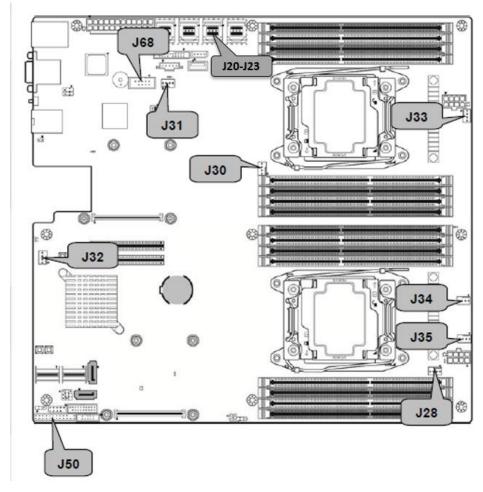
Description	Pi	in#	Description
100MHZ_CLK_P	A1	C1	SMB_SDA
100MHZ_CLK_N	A2	C2	SMB_SCL
GND	A3	C3	GND
PCIE_RX_P2	A4	C4	PCIE_TX_P2
PCIE_RX_N2	A5	C5	PCIE_TX_N2
GND	A6	C6	GND
PCIE_RX_P0	A7	C7	PCIE_TX_P0
PCIE_RX_N0	A8	C8	PCIE_TX_N0
GND	A9	C9	GND
PCIE_RESET_N	B1	D1	SB_SMB_SDA
NC	B2	D2	SB_SMB_SCL
GND	B3	D3	
PCIE_RX_P3	B4	D4	PCIE_TX_P3
PCIE_RX_N3	B5	D5	PCIE_TX_N3
GND	B6	D6	
PCIE_RX_P1	B7	D7	PCIE_TX_P1
PCIE_RX_N1	B8	D8	PCIE_TX_N1
GND	B9	D9	GND
MTG_GND	G1	G3	MTG_GND
MTG_GND	G2	G4	MTG_GND

A1 A2 A3 A4 A5 A6 A7 A8 A9	A1 A2 A3 A4 A5 A6 A7 A8 A9	C1 C2 C3 C4 C5 C6 C7 C8 C9	C1 C2 C3 C4 C5 C6 C7 C8
B1 B2 B3 B4 B5 B6 B7 B8 B9	B1 B2 B3 B4 B5 B6 B7 B8 B9	D1 D2 D3 D4 D5 D6 D7 D8	D1 D2 D3 D4 D5 D6 D7 D8 D9
G1 G2	G1 G2	G3 G4	G3 G4
	MINISAS	_HDX1-	36P

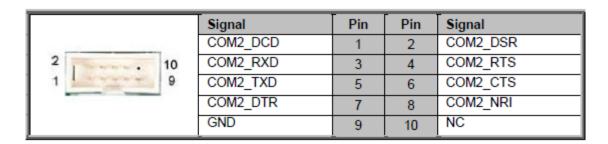








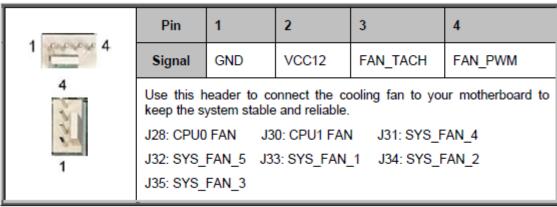
J68: COM Port Header:



J28/J30/J31/J32/J33/J34/J35: 4-pin FAN Connector:





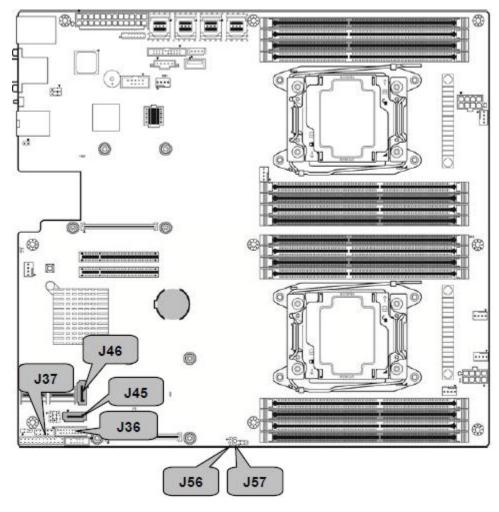


J50: Front Panel Header:

	Signal	Pin	Pin	Signal
	FP_PW_LED_PW	1	2	FP_PWR
	KEY	3	4	FP_ID_LED_PW
l	PWR_LED-	5	6	FP_ID_LED_N
	HDD_LED+	7	8	LED_FAULT1
23 1	HDD_LED-	9	10	LED_FAULT2
	FP_PWRSW#	11	12	LAN0_ACT_P
24 2	GND	13	14	LAN0_LED1_ACT#
	FP_RSTSW#	15	16	FP_SMBDAT
	GND	17	18	FP_SMBCLK
1	FP_IDLEDSW#	19	20	FP_INTRUSION#
l	NC	21	22	LAN1_ACT_P
	FP_NMISW#	23	24	LAN1_LED1_ACT#







J56: Front Panel ID LED:

PIN1 ■ ■	Signal	Pin	Pin	Signal
	FP_IDLEDSW#	1	2	GND

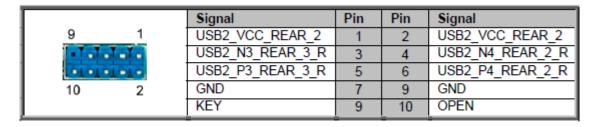
J57: Chassis Intrusion Header:

PIN1	Signal	Pin	Pin	Signal
	INTRUDER#	1	2	GND





J37: Front USB2.0 Header (Blue):



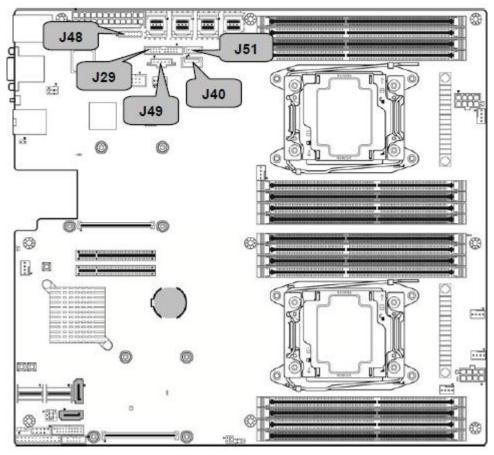
J45/J46: 7-pin Vertical SATA3.0 Connector:

	PIN Define	Pin	
7 🗉	1	GND	Connects to the Serial
	2	SATA_TXP_C	ATA ready drives via
	3	SATA_TXN_C	the Serial ATA cable.
	4	GND	
 	5	SATA_RXN_C	J45: SATA4
 1 ■	6	SATA_RXP_C	J46: SATA5
	7	GND	

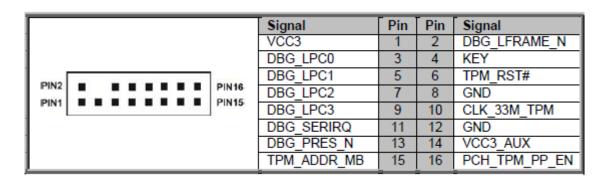
J36: USB3.0 Header:

	Signal	Pin	Pin	Signal
l	USB3_VCC_FPB_01	1	20	KEY
l	USB3_N5_RX_FPB_N0	2	19	USB3_VCC_FPB_01
l	USB3_P5_RX_FPB_P0	3	18	USB3_N6_RX_FPB_N1
l	GND	4	17	USB3_P6_RX_FPB_P1
1 10	USB3_N5_TX_FPB_N0	5	16	GND
20 11	USB3_P5_TX_FPB_P0	6	15	USB3_N6_TX_FPB_N1
	GND	7	14	USB3_P6_TX_FPB_P1
l	USB2_N12_FPB_N0_R	8	13	GND
	USB2_P12_FPB_P0_R	9	12	USB2_N11_FPB_N1_R
]	OC_N	10	11	USB2_P11_FPB_P1_R





J48: TPM Module Header:



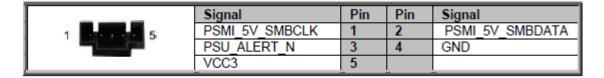
J40: Vertical Type-A USB Connector:

	Signal	Pin	Pin	Signal
	USB_VCC_TYPE_A	1	2	USB_N2_TYPE_A1_R
المستما	USB_P2_TYPE_A1_R	3	4	GND





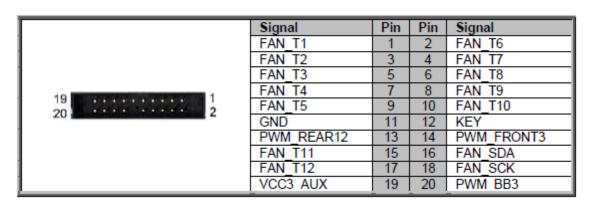
J49: PSMI Connector:



J51: IPMB PIN Header:

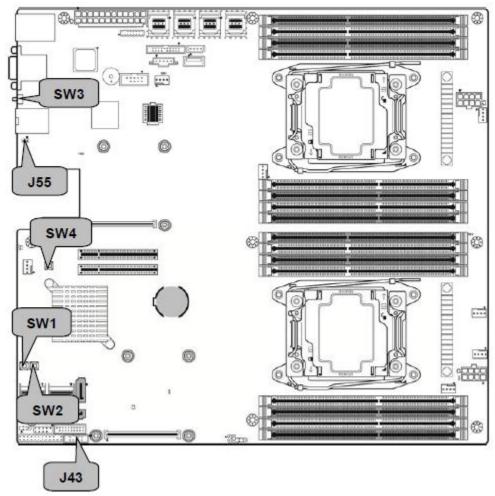
1	Pin	1	2	3	4
1 4	Signal	IPMB DATA	GND	IPMB CLK	VCC

J29: Fan Connector Reserved for Barebone:

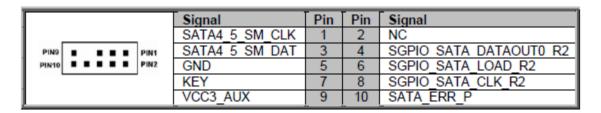








J43: PCH SGPIO PIN Header:



J55: BMC Reset Header:

PIN1 ■ ■	Signal	Pin	Pin	Signal
PINT	BMC_JP_N	1	2	GND





SW3 (J56): ID LED Switch Button:

Signal	Pin	Pin	Signal
FP_IDLED_BTN_N	1	2	GND
GND	3	4	GND

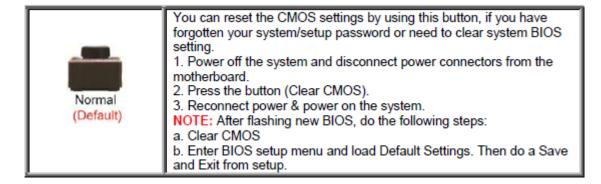
SW1: Power Switch Button:

	Signal	Pin	Pin	Signal
	FP_PWR_BTN_N	1	2	FP_PWR_BTN_N
Normal (Default)	GND	3	4	GND

SW2: Reset Switch Button:

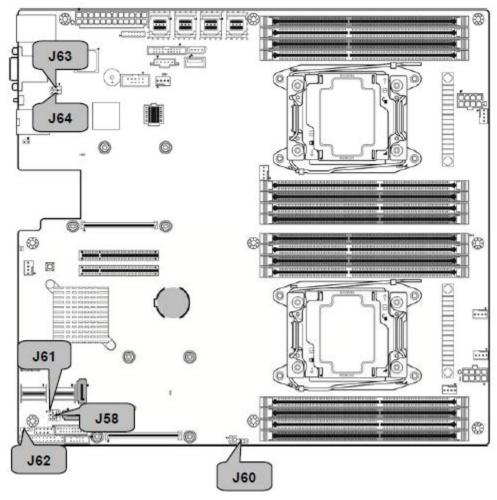
	Signal	Pin	Pin	Signal
	FP_RST_BTN_N	1	2	FP_RST_BTN_N
Normal (Default)	GND	3	4	GND

SW4: Clear CMOS Reset Button:

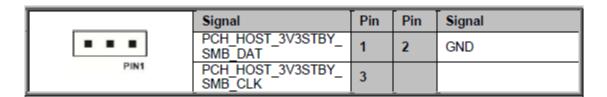




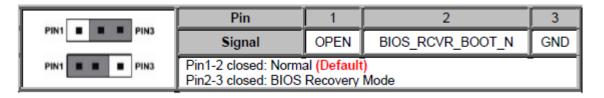




J61: HOST SMB Header:



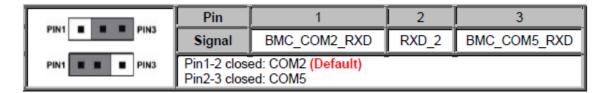
J58: BIOS Recovery Mode Jumper:



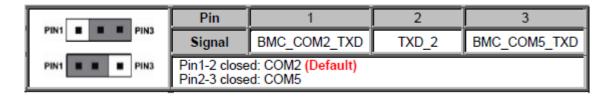




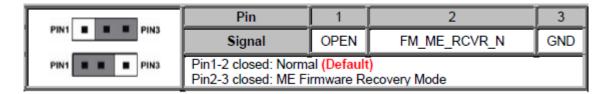
J63: COM2 or COM5 Selected Jumper:



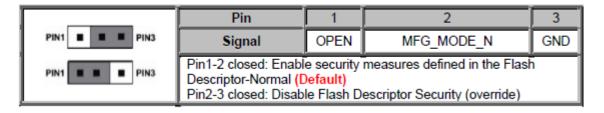
J64: COM2 or COM5 Selected Jumper:



J62: ME Firmware Recovery Mode Jumper:

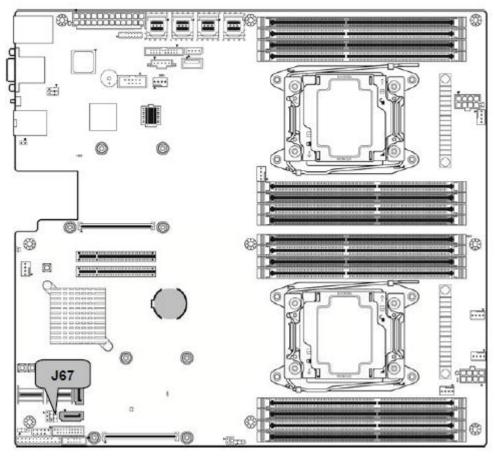


J60: Flash Descriptor Security Override Header:

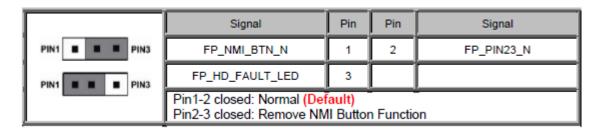








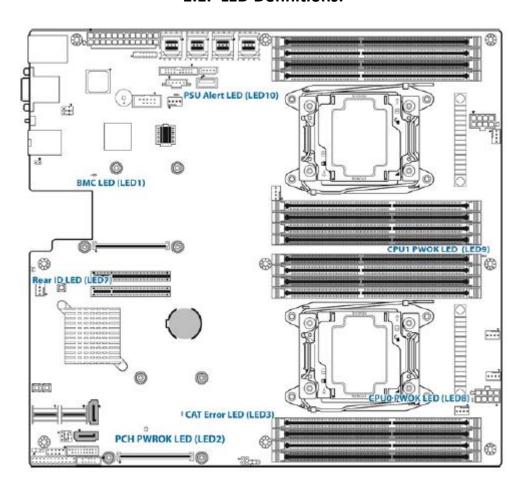
J67: NMI Jumper:







1.1. LED Definitions:





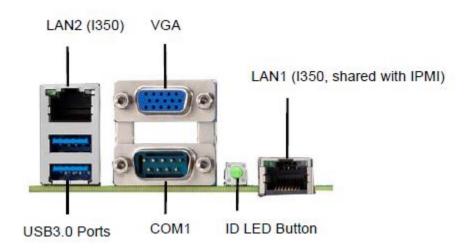


		Pin	Signal			
1		+	+3V AUX			
1		-	GND			
1		State	Description			
LED1	BMC Heart Beat LED	OFF	OFF	The LED shuts off when the BMC controller cannot be detected or properly initiated.		
		Blinking	Green	The LED blinks per second to indicate that the BMC controller is working normally		
		Pin	Signal			
		+	+3V			
]		-	GND			
LED2	PCH PWOK	State	Description			
	LED	OFF	OFF	The LED shuts off when the power of PCH is abnormal.		
		ON	Amber	The amber LED lights up when the power of PCH is normal.		
		Pin	Signal			
]		+	+3V			
]		-	GND			
		State	Description			
LED3	CAT Error LED	OFF	OFF	The LED shuts off when System is running normally.		
		ON	Red	The LED lighted up when the system has experienced a fatal or catastrophic error and can not continue to operate.		
		Pin	Signal			
		+	+ VCC3 AUX			
LED7	Rear ID	-	GND			
1	LED	State	Description			
Į.		OFF	OFF	OFF		
		ON	Green	ON		
		Pin	Signal			
Į.		+	+3V			
LED8	CPU0	-	GND			
1	PWOK LED	State	Description			
Į.		OFF	OFF	OFF		
J.		ON	Green	ON		





		Pin	Signal	
1		+	+ 3V	
1	CDLI4	-	GND	
LED9	CPU1 PWOK LED	State	Description	
	PWORLLD	OFF	OFF	The LED shuts off when the power of CPU1 is abnormal.
		ON	Green	The LED lights up when the power of CPU1 is normally.
		Pin	Signal	
1		+	+ VCC3_AUX	
]	DOLL Mark	-	GND	
LED10	PSU Alert LFD	State	Description	
		OFF	OFF	The LED shuts off when the PSU is normal.
		ON	Green	The LED lights up when the PSU is abnormally.



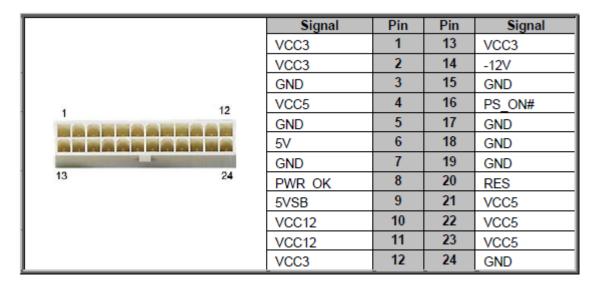
10/100/1000 Mbps LAN Link/Activity LED Scheme					
LEFT RICHT		Left LED	Right LED		
10 Mhna	Link	Green	Off		
10 Mbps	Active	Blinking Green	Off		
400 141	Link	Green	Solid Green		
100 Mbps	Active	Blinking Green	Solid Green		
4000 111	Link	Green	Solid Yellow		
1000 Mbps	Active	Blinking Green	Solid Yellow		
No	Link	Off	Off		







PW2: ATX 24-pin Main Power Connector



PW1: SSI 8-PIN CPU0 Power Connector

1 4	Signal	Pin	Pin	Signal
TAGE !	GND	1	5	P0_P12V
8888	GND	2	6	P0_P12V
	GND	3	7	P0_MEM_P12V
5 8	GND	4	8	P0_MEM_P12V

PW3: SSI 8-PIN CPU1 Power Connector

1 4	Signal	Pin	Pin	Signal
TA A H	GND	1	5	P1_P12V
0000	GND	2	6	P1_P12V
The state of the s	GND	3	7	P1_MEM_P12V
5 8	GND	4	8	P1_MEM_P12V

10. PSU Module(s)

The power supply dimension is $73.5(W) \times 40/39(H) \times 196(L)$ mm, including the golden finger portion. The PSU form factor must have a lock mechanism and a line cord holder. The air intake is from the golden finger side with the exhaust is located on the AC connector side.

Input – The AC input is done via an IEC 320 C-14 power inlet. This inlet is rated for 10A / 250VAC. This connector is located at the front side of the power supply. The PSU is designed to enable system implementation that uses multiple-phase AC input power. In





this configuration, not all power supplies in a system are required to be on the same AC input phase.

Efficiency – The power supply has a minimum efficiency according to the below table. At zero load condition, the PSU must realize minimized losses. The fan losses are not included in the efficiency calculation and measurements.

	10% Load	20% Load	50% Load	100% Load
230VAC/50Hz	82%	90%	94%	91%

Fuse – The power supply has a 16A fast blow type fuse. The AC line fuse must be accepted by all safety agencies. AC inrush current and all protection circuits in the power supply do not cause the AC fuse to blow unless a component in the power supply has failed.

AC Line Dropout – An AC line dropout is defined to be when the AC input drops to 0VAC at any phase of the AC line for any length of time. During an AC dropout of 10ms or less at any phase of AC voltage, the power supply meets dynamic voltage regulation requirements over the rated load. An AC line dropout of 10ms or less does not cause any tripping of control signals or protection circuits. If the AC dropout lasts longer than 10ms, the power supply recovers and meets all turn-on requirements.

DC Output Connector – The output gold finger connector connects the power as well as the signal to the system or power backplane board. The Signal description is defined as follows:

Signal	Description	
+12V	+ 12V output	
+12VSB	+ 12V standby output	
GND	0V ground	
12LS	+ 12V load share bus	
12VRS	+ 12V remote sense	
RETURN_S	OV remote sense	
PWOK	Power ok output	
PSON	Power disable input	
SCL	SMBus Clock	

Voltage Regulation – The power supply voltage must stay within the following voltage limits when operating at steady state load conditions. These limits do not include the peak-peak ripple/noise. All outputs are measure with reference to the +12VRS and RETURN_S signal. The +12VSB is measured at the output connector.

Static Regulation				
Min Nom Max Tolerance				
+12V	11.4V	12.0V	12.6V	+5% / -5%
+12VSB	11.4V	12.0V	12.6V	+5% / -5%

Dynamic Regulation				
Min Max Tolerance				
+12V	11.4V	12.6V	+5% / -5%	
+12VSB	11.4V	12.6V	+5% / -5%	





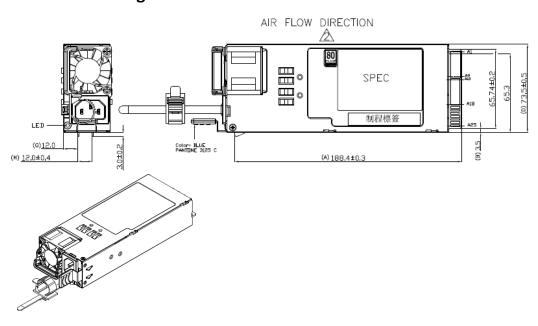
	Step Load Size	Slew Rate	Capacitive Load
+12V	60% of max load	0.5A/μsec	2200μF
+12VSB	0.5A	0.5A/μsec	22μF

Audible Noise – No abnormal audible noise is allowed to be generated by the power supply.

Residual Voltage – The PSU should be immune to be any residual voltage placed on its outputs (typically a leakage voltage through the system from standby output) up to 500mV. There shall be no additional heat generated, nor stressing of any internal components with this voltage applied to any individual or all outputs simultaneously.

Protection Circuits – Protection circuits inside the power supply cause only the power supply's main outputs to shut down. The +12VSB output remains powered on if the failure does not involve this output. When a protection circuit shuts down the power supply, the PWOK signal will go LOW, the bi-color LED will change from GREEN to YELLOW. If the power supply latches off due to a protection circuit tripping, an AC cycle OFF for less than 15sec initiated via PSON or PMBus Command ON/OFF for less than 2sec is able to reset the power supply.

PSU CAD Drawings -



PSU Part #s - Delta DPS-500AB-17 B, Delta DPS-650XB-2 G





11. Mechanical

The Hyve Solutions Ambient Series-E servers are configurable with single or redundant power supply. Both 3.5" and 2.5" drives are supported.

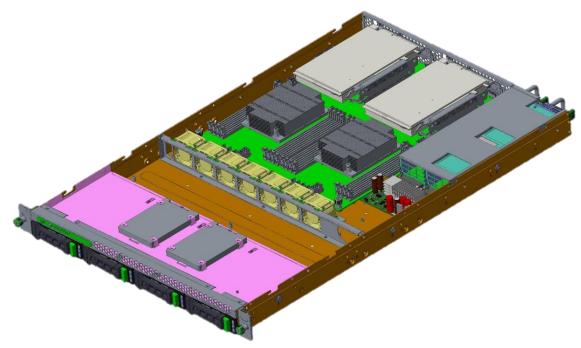


Figure 5: Ambient Series-E 1x4 with redundant PSU

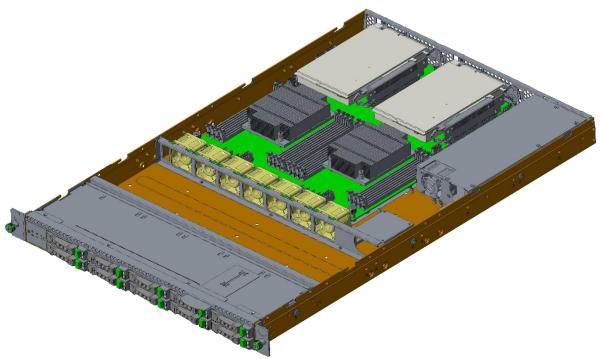


Figure 6: Ambient Series-E 1x10 with single PSU





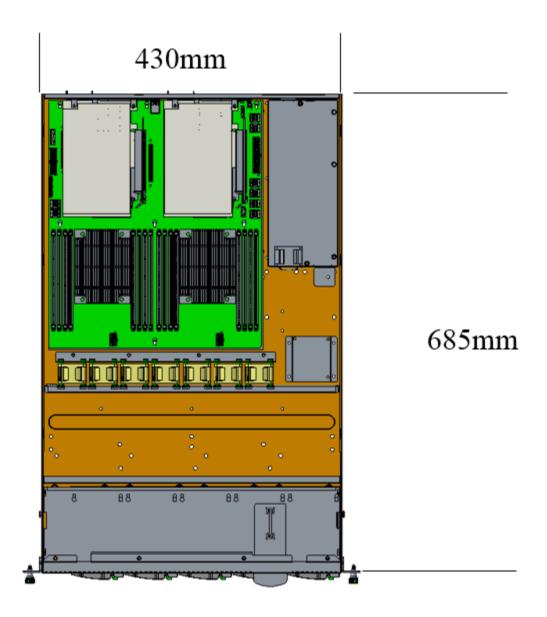




Figure 5:Ambient Series-E chassis dimensions





The Hyve Solutions Ambient Series-E servers make use of copper or aluminum passive heatsinks.





• Copper Dimensions: 104 mm (L) x 65 mm (W) x 24 mm (H)

• Aluminum Dimensions: 106mm (L) x 80mm (W) x 27 mm (H)

• Materials: Copper / Aluminum

Fin Pitch: 1.9 mm
Fin height: 21 mm
Fin thickness: 0.4 mm

• Heatsink Base Thickness: 6 mm

• Weight: 425 g (Copper) 260g (Aluminum)

12. Environmental Requirements

The system meets the following environmental requirements:

- Gaseous Contamination: Severity Level G1 per ANSI/ISA 71.04-1985
- Ambient operating temperature range: -5°C to +45°C
- Operating and storage relative humidity: 10% to 90% (non-condensing)
- Storage temperature range: -40°C to +70°C
- Transportation temperature range: -55°C to +85°C (short-term storage)

The Hyve Solutions Ambient Series-E has an operating altitude with no de-ratings of 1000m (3300 feet).





13. Vibration and Shock

The system meets shock and vibration requirements according to ICE specifications: IEC7802 and IEC721-3 Standard & Levels. The testing requirements are listed below:

	Operating	Non-Operating
Vibration	0.5G acceleration, 1.5mm amplitude, 5 to 500 Hz, 10 sweeps at 1 octave / minute for each of the three axes	1g acceleration, 3mm amplitude, 5 to 500 Hz, 10 sweeps at 1 octave / minute for each of the three axes
Shock	6g, half-sine 11mS, 5 shocks for each of the 3 axes	12g, half-sine 11mS, 10 shocks for each of the three axes

14. Prescribed Materials

14.1 Disallowed Components

The following components are not used in the design of the motherboard:

- Components disallowed by the European Union's Restriction of Hazardous Substances Directive (RoHS 6)
- Trimmers and/or potentiometers
- Dip switches

14.2 Capacitors and Inductors

The following limitations apply to the use of capacitors:

- Only aluminum organic polymer capacitors made by high quality manufacturers are used; they must be rated at 105°C
- All capacitors have a predicted life of at least 50,000 hours at 45°C inlet air temperature, under worst conditions
- Tantalum capacitors using manganese dioxide cathodes are forbidden
- SMT ceramic capacitors with case size > 1206 are forbidden (size 1206 are still allowed when installed far from the PCB edge and with a correct orientation that minimizes risk of cracks)
- Ceramic material for SMT capacitors must be X7R or better material (COG or NPo type should be used in critical portions of the design)

Only SMT inductors may be used. The use of through-hole inductors is disallowed.